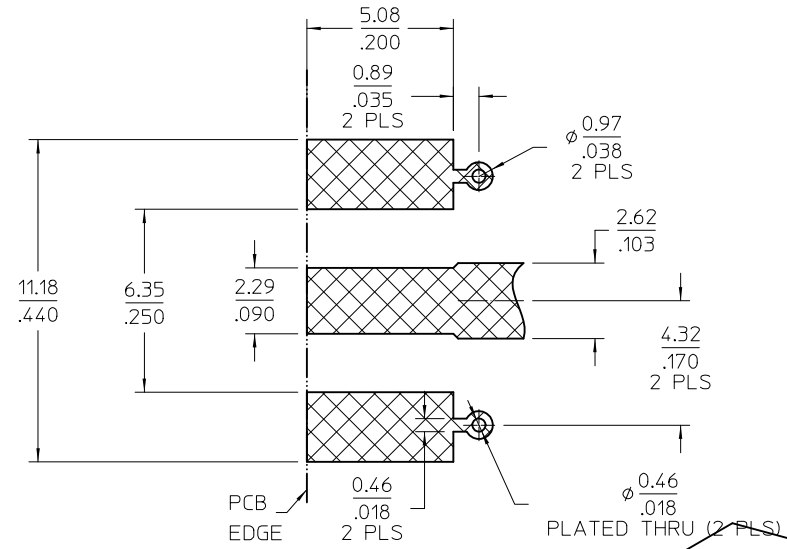
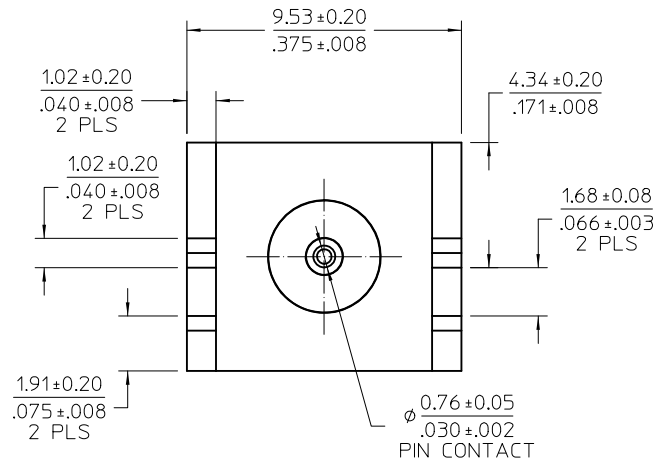
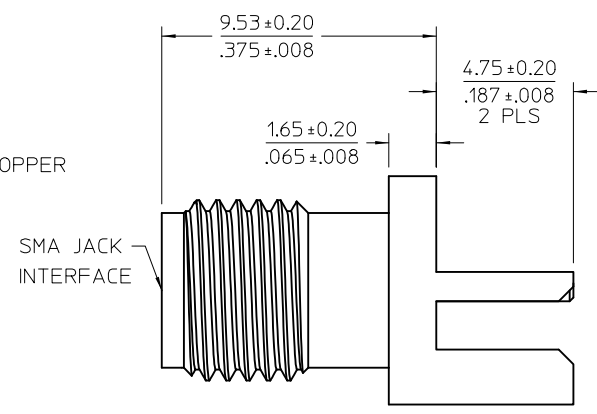
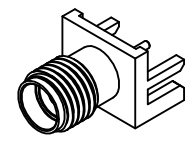


MATERIALS AND FINISHES

BODY BRASS
PLATED GOLD (SEE TABLE)

CENTER CONTACT BERYLLIUM COPPER
PLATED GOLD (SEE TABLE)

INSULATOR TEFLON



RECOMMENDED MOUNTING PAD

BASE WIDTH: 9.53(.375)
BOARD THICKNESS: 1.57(.062)
BOARD MATERIAL: FR4 W/28 g(1.0 OZ) COPPER
ON BOTTOM (GROUND) SIDE

PRE-RELEASE
REFERENCE
USE ONLY

PS-89675-2820	ELEC/MECH PERFORMANCE
MIL-STD-348A, FIG. 310.2	INTERFACE
SPECIFICATION	DESCRIPTION

73251-1153	GOLD FLASH	GOLD 5μ"	TRAY (80 PIECES)
73251-1152	GOLD	GOLD	TRAY (20 PIECES)
73251-1151	GOLD	GOLD	ONE 73251-1150 PER BAG
73251-1150	GOLD	GOLD	TRAY (80 PIECES)
PART NO.	BODY PLATING	CONTACT PLATING	PACKAGING
DIM X			

CHG: ADDED -1153 PER PDR1103766 EC NO: 2011/03/23 DRAWING: 102 CHKD: APPR: REV:	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM/IN		SCALE	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± --- ± ---	1 PLACE ± --- ± ---	DRAWN BY TEF	DATE 2002/06/27	TITLE SMA JACK, EDGE MOUNT 50 OHMS, EWR-1764 SMA-J/PCB		
		ANGULAR ± 2 °				CHECKED BY SSS	DATE 2002/06/27	MOLEX INCORPORATED		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				APPROVED BY GMH	DATE 2002/06/27	MATERIAL NO.	DOCUMENT NO.	SHEET NO. 1 OF 1